



## Addendum

**Product Name:** FireLink 82C861 PCI-to-USB Bridge  
**Document:** FireLink Data Book rev. 1.0 912-3000-049  
**Date:** October 3, 2000

### Marking Specifications

Some product specifications that are missing from the 82C861 rev. 1.0 data book are provided in this document.

#### Package Marking

Specific marking for the production 82C861 rev. 1.0 silicon package is as follows, for both PQFP and LQFP (not to scale):



where:

- 14 indicates OPTi netlist revision 1.4
- yy indicates the year of production
- ww indicates the week of production (1-52)
- 10 indicates foundry mask revision 1.0
- U indicates the foundry as UMC
- E indicates the assembly house as ASE.

#### Order Number and Shipping Box Information

Specific marking for the box in which the 82C861 silicon is shipped is as follows:

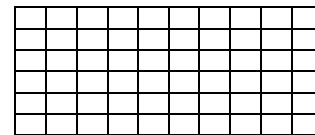
QP0086110XUE-002 – Identifies that the box contains PQFP packaged parts (shown as Figure 7-2 in Data Book) from a normal production run (-002). 10XUE indicates the same as the 10UE on the chip marking; the "X" indicates no particular speed grading.

QT0086110XUE-002 – same as above, but for LQFP packaged parts (shown as Figure 7-1 in Data Book).

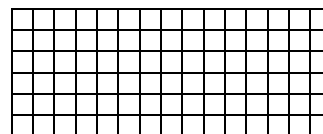
These are also the numbers used to order parts from OPTi.

**Packing Options.** All packing is done in trays only. Trays measure 13.5mm x 32.2mm for both PQFP and LQFP.

- For PQFP package:  
66 parts per tray, 10 trays per box



- For LQFP package:  
90 parts per tray, 10 trays per box



- Baking method: 125°C for 12 hours.

### Package Specifications

**Package Thermal Specifications.** For both PQFP and LQFP packages, worst-case values are as follows:

- $\theta_{JA}$  = 40 °C/W at no air flow
- $\theta_{JC}$  = 5 °C/W
- Max power output = 1.5W at 25 °C.

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**Packaging Details.** For both package types:

- LEAD FRAME: C7025 (Cu)
- SOLDER: Sn/Pb = 85/15
- WIRE BOND: Gold Wire (99.99% Au)
- Resistance to flow, spot, or IR reflow soldering heat:  
255°C for 5s max.

For PQFP package:

- EPOXY: ABLESTIK 8360
- MOLDING COMPOUND: Sumitomo EME-6600 CS

For LQFP package:

- EPOXY: ABLESTIK 8361H
- MOLDING COMPOUND: Sumitomo EME-7320A(R)

**Environmental Details.**

- Electrostatic Discharge (ESD) Tolerance: 2000V

## Data Book Correction

**Reset Pin Direction.** In Section 3.2.1, the RESET# Pin Type is incorrectly identified as “O” for Output. It should be listed as “I” for Input.